

Product Data Sheet Type: FI340/31,8/SL/T

Group: HEATSINKS Board Level

For single mounting

Width :	40.5 mm
Height :	31.8 mm
Length :	46 mm
Minimum thermal resistance :	4,8 K/W
For device :	TO 3
Device mounted by :	Screw
Heatsink mounted by :	Srew-On
Surface :	Blackened
Material :	AlSiCu 3



Finger shaped heatsink from die-casting aluminium with or without hole pattern for semiconductor case TO3.

Standard heights: 12,7; 19,1; 25,4; and 31,8 mm.

Space saving construction.

Turbulence in every installation position.

